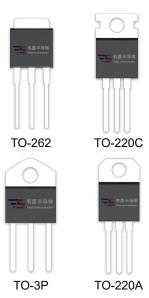


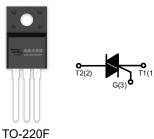
### **DESCRIPTION:**

With high ability to withstand the shock loading of large current, BTB24-800BW series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.



### **MAIN FEATURES**

Symbol Value		Unit
I <sub>T(RMS)</sub>	25	A
V <sub>DRM</sub> /V <sub>RRM</sub>	600/800/1200/1600	V



### **ABSOLUTE MAXIMUM RATINGS**

Parameter		Symbol	Value	Unit
Storage junction temperature range		T <sub>stg</sub>	-40-150	$^{\circ}$ C
Operating junction	Operating junction temperature range		-40-125	$^{\circ}\!\mathbb{C}$
Repetitive peak of	f-state voltage (T <sub>j</sub> =25℃)	$V_{DRM}$	600/800/1200/1600	V
Repetitive peak re	verse voltage (T <sub>j</sub> =25℃)	V <sub>RRM</sub>	600/800/1200/1600	V
RMS on-state current	TO-220A(Ins)/ TO-220F(Ins) (Tc=70°C) TO-220C/ TO-220A(Non-Ins) (Tc=85°C) TO-262 (Tc=50°C) TO-3P(Ins) (Tc=95°C)	I <sub>T(RMS)</sub>	25	A
Non repetitive surge peak on-state current (full cycle, F=50Hz)		Ітѕм	250	А
I <sup>2</sup> t value for fusing (tp=10ms)		l <sup>2</sup> t	340	A <sup>2</sup> s



Critical rate of rise of on-state current $(I_G = 2 \times I_{GT})$	dl/dt	50	A/µs
Peak gate current	Ідм	4	Α
Average gate power dissipation	P <sub>G(AV)</sub>	1	W
Peak gate power	P <sub>GM</sub>	10	W

# **ELECTRICAL CHARACTERISTICS** ( $T_j$ =25 $^{\circ}$ C unless otherwise specified)

V<sub>DRM</sub> /V<sub>RRM</sub>: 600/800V

Symbol	Test Condition	Quadrant		JST24-600/800V		Unit
				BW	CW	Uill
lgт	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	I - II -III	MAX	50	35	mA
V <sub>G</sub> T	VD - 12V KL - 3312	I - II -III	MAX	1	.3	V
V <sub>GD</sub>	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	I - II -III	MIN	0.2		V
IL	I <sub>G</sub> =1.2I <sub>GT</sub>	I -III	MAX	80	70	mA
		II	IVIAA	100	80	IIIA
Ін	I <sub>T</sub> =100mA		MAX	75	50	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃		MIN	1000	500	V/µs

V<sub>DRM</sub> /V<sub>RRM</sub>: 1200/1600V

Symbol	Test Condition Quad	Quadrant	Quadrant	JST24-1200V/1600V		Unit
		Quaurant		BW	CW	Oilit
lgт	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	I - II -III	MAX	50	35	mA
V <sub>G</sub> T	VD-12V KL-3312	I - II -III	MAX	1	.5	V
V <sub>GD</sub>	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	I - II -III	MIN	0.2		V
1.	I <sub>G</sub> =1.2I <sub>GT</sub>	I -III	MAX	90	70	mA
IL.		II	IVIAA	100	80	IIIA
Ін	I <sub>T</sub> =100mA		MAX	80	60	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃		MIN	1500	1000	V/µs



V<sub>DRM</sub> /V<sub>RRM</sub>: 600/800V

Symbol	Test Condition	Quadrant		JST24-600/800V		Unit
				В	С	Unit
		I - II -III	MAY	50	25	m 1
I <sub>GT</sub>	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	IV	MAX	70	50	mA
V <sub>GT</sub>		ALL	MAX	1	.3	V
V <sub>GD</sub>	$V_D = V_{DRM} T_j = 125^{\circ}C$ $R_L = 3.3 K\Omega$	ALL	MIN	0.2		V
I.	I <sub>G</sub> =1.2I <sub>GT</sub>	I -III-IV	MAX	80	70	mΛ
l L		II	IVIAA	100	90	mA
I <sub>H</sub>	I <sub>T</sub> =100mA		MAX	75	60	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃		MIN	500	200	V/µs

## **STATIC CHARACTERISTICS**

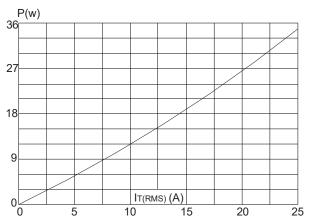
Symbol	Parameter		Value(MAX)	Unit
V <sub>TM</sub>	I <sub>тм</sub> =35A tp=380µs	T <sub>j</sub> =25℃	1.5	V
IDRM	\\ _\\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\	T <sub>j</sub> =25℃	5	μΑ
I <sub>RRM</sub>	$V_D = V_{DRM} V_R = V_{RRM}$	T <sub>j</sub> =125℃	3	mA

### **THERMAL RESISTANCES**

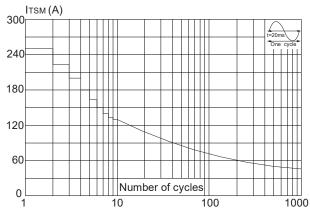
Symbol	Parame	Value	Unit	
		TO-220A(Ins)	1.5	
	junction to case(AC)	TO-220C/ TO-220A(Non-Ins)	1.1	°C/W
Rth(j-c)		TO-220F(Ins)	1.7	
		TO-262	2.1	
		TO-3P(Ins)	0.67	



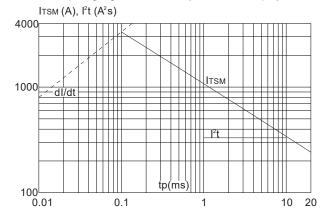
**FIG.1:** Maximum power dissipation versus RMS on-state current



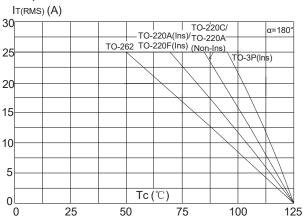
**FIG.3:** Surge peak on-state current versus number of cycles



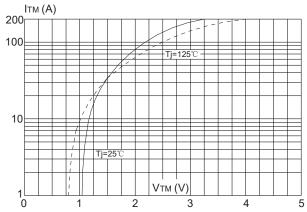
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms, and corresponging value of I<sup>2</sup>t (dI/dt < 50A/µs)



**FIG.2:** RMS on-state current versus case temperature



**FIG.4:** On-state characteristics (maximum values)



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature

